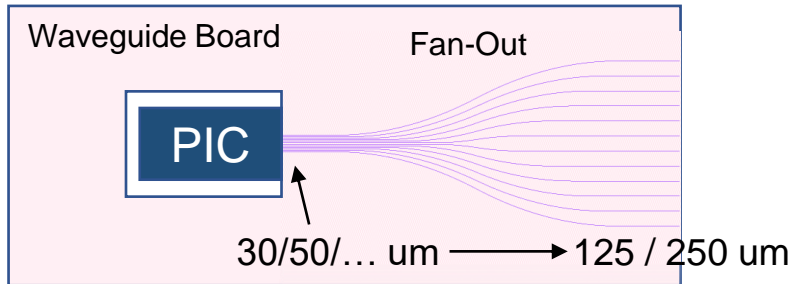


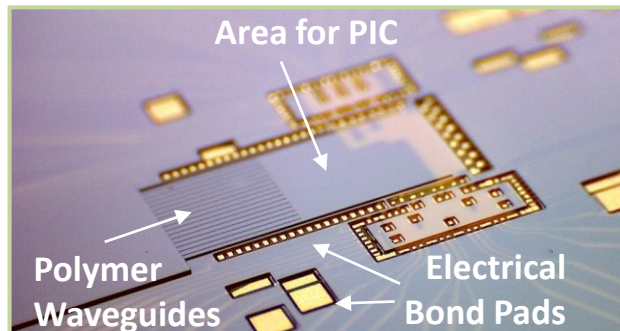
next-gen hybrid PIC integration

1 Platform for several PICs/Components

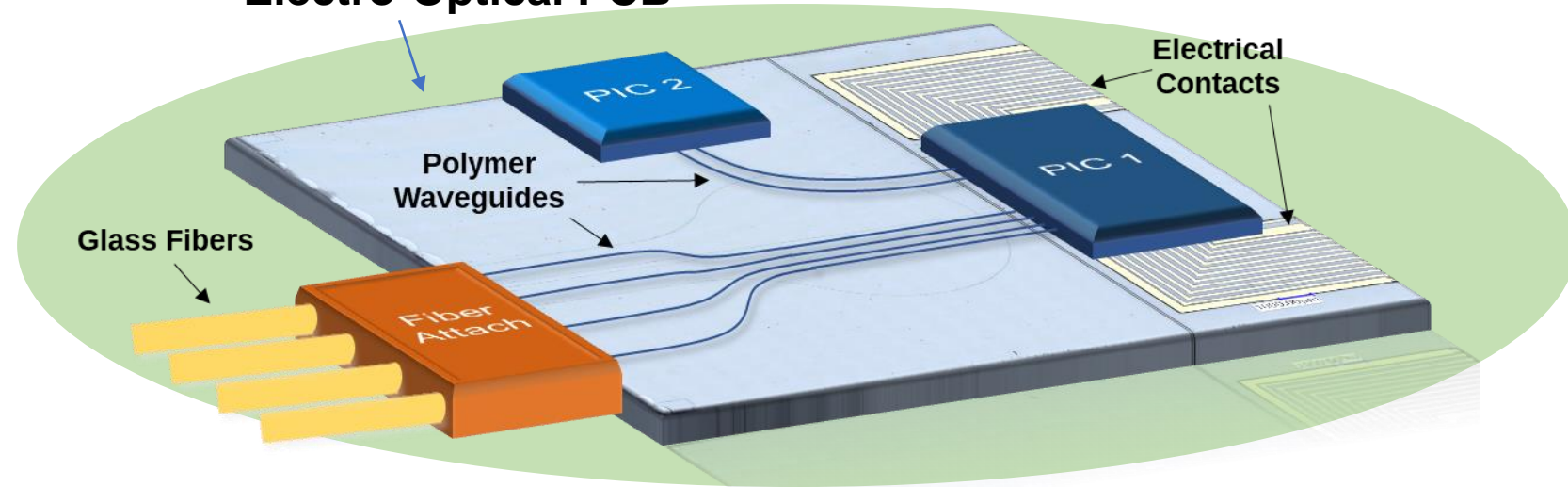
- **Planar Waveguides:**
 - On-board light routing
 - High I/O number optical Fan-outs
 - Polarization maintaining Waveguides



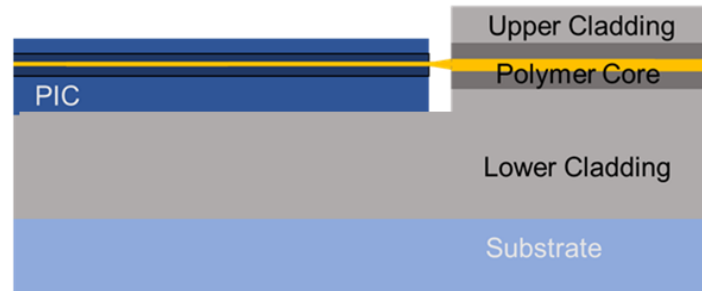
- **Combination with PCB**
 - Electro-optical co-packaging, RF (100GHz)
 - metallization on photonic substrate
 - thermal-vias for heat dissipation



Electro-Optical PCB



- **Butt-coupling / adiabatic interface**
 - with passive Z-Alignment,
 - relaxed tolerance (+/- 2um)
 - On-chip mode conversion (e.g. SiPh to Fiber)



What we offer:

Unique platform for **all-in-one approach** to PIC packaging
 -> multi-chip, multi-port architectures

What we are looking for:

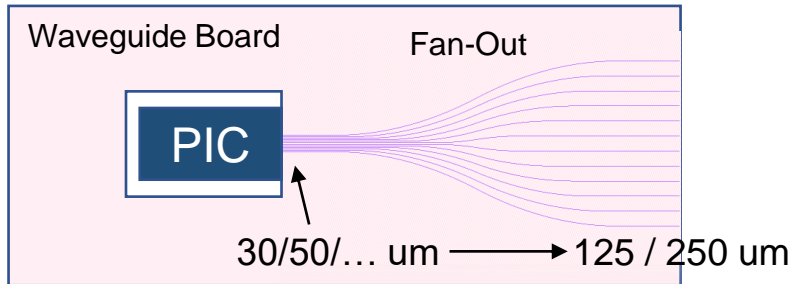
Feedback / Partners in order to further develop&test this platform

next-gen hybrid PIC integration

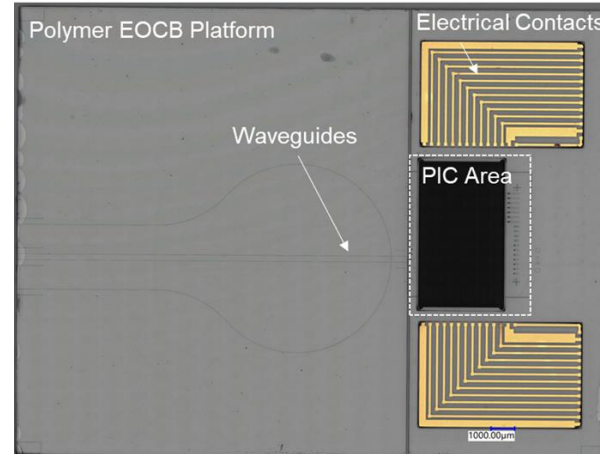
1 Platform for several PICs/Components

- **Planar Waveguides:**

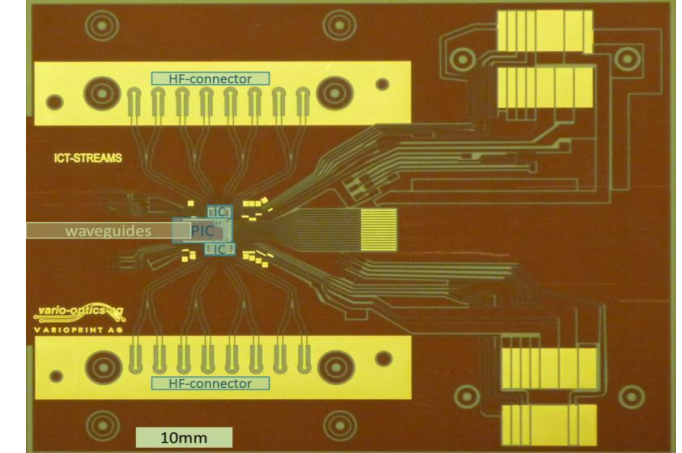
- On-board light routing
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- Polarization maintaining Waveguides



Example1: glass substrate, ICT-QAMeleon project

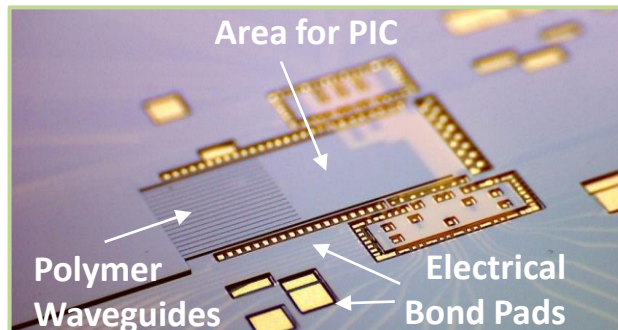


Example2: RF PCB, ICT-STREAMS project



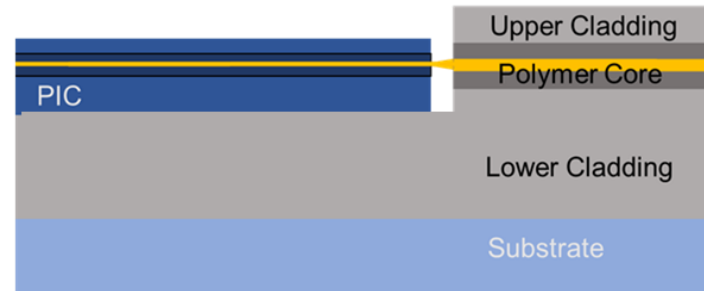
- **Combination with PCB**

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